

Title (en)  
POWDER AND PASTE FOR IMPROVING THE CONDUCTIVITY OF ELECTRICAL CONNECTIONS

Title (de)  
PULVER UND PASTE ZUR ERHÖHUNG DER LEITFÄHIGKEIT ELEKTRISCHER VERBINDUNGEN

Title (fr)  
POUDRE ET PÂTE POUR AMÉLIORER LA CONDUCTANCE DES CONNEXIONS ÉLECTRIQUES

Publication  
**EP 2904615 B1 20190508 (FR)**

Application  
**EP 13780184 A 20131002**

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Abstract (en)  
[origin: WO2014053715A1] An electrical connection powder comprising particles obtained by pulverising a skeleton of open cell metal foam chosen from the group consisting of iron, cobalt, nickel and the alloys of same covered with at least one coating of tin or indium or one of the alloys of same. The paste is formed from this powder dispersed in a binder such as grease. The powder or paste is particularly useful for improving the conductivity of an electrical connection consisting of a terminal (20) linked to a cable (24) consisting of a plurality of strands (30, 32, 34) by means of a crimping ring (26).

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